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Application Serial No. 09/756,971  
Response to 02/05/04 OA

MI22-1572

2827  
IFW

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Serial No. .... 09/756,971  
Filing Date ..... January 9, 2001  
Inventor ..... Salman Akram  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 2827  
Examiner ..... D.A. Zarneke  
Attorney's Docket No. .... MI22-1572  
Title:     Methods of Forming Board-On-Chip Packages

**RESPONSE TO FEBRUARY 5, 2004 OFFICE ACTION**

To:           Mail Stop Amendment  
              Commissioner for Patents  
              P.O. Box 1450  
              Alexandria, VA 22313-1450

From:       D. Brent Kenady  
              Tel. 509-624-4276; Fax 509-838-3424  
              Wells St. John P.S.  
              601 West First Avenue, Suite 1300  
              Spokane, WA 99201-3828

Responsive to the Office Action dated February 5, 2004, Applicant amends  
and remarks as follows:

**AMENDMENTS**

Underlines indicate insertions and ~~strikeouts~~ indicate deletions.